

Solder paste product lineup

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| | Product name | Feature | Alloy composition | Powder size (μm) | Viscosity (Pa·s) |
|----------------------|--------------------------------------|--------------------------------|----------------------------------|------------------|------------------|
| Automotive | GSP | Automotive for general purpose | Sn-3.0Ag-0.5Cu | 20-38 | 160 |
| | CLR | Excellent printability | Sn-3.0Ag-0.5Cu | 20-38 | 220 |
| | PS48BR-600-LSP | High durability | Sn-3.2Ag-0.5Cu-4.0Bi-3.5Sb-Ni-Co | 20-38 | 220 |
| | PS31B-600-HC1 | Halogen free | Sn-3.0Ag-0.5Cu | 20-38 | 200 |
| | PS31BR-600A-VHICS | Washable and voidless | Sn-3.0Ag-0.5Cu | 20-38 | 200 |
| | PS10B-600A-ANI-1 | Tin-lead for general purpose | Sn-37Pb | 20-38 | 200 |
| | PS60B-450A-TR5 | Tombstone improved | Sn-36Pb-2Ag | 20-38 | 200 |
| Consumer electronics | PS31BR-600A-HVS3 PS31BR-700A-HVS3 | Lead-free for general purpose | Sn-3.0Ag-0.5Cu | 20-38 15-25 | 180 |
| | PS31BR-600-NH5 | Halogen free | Sn-3.0Ag-0.5Cu | 20-38 | 200 |
| | PS31BR-600-NH11 | | Sn-3.0Ag-0.5Cu | 20-38 | 170 |
| | PS31BR-600A-LH1 | | Sn-3.0Ag-0.5Cu | 20-38 | 200 |
| | PS31BR-800-FC1 | 0201 chip soldering | Sn-3.0Ag-0.5Cu | 5-15 | 210 |
| | PS24BR-600A-HLS7 | Low 1.1% silver | Sn-1.1Ag-0.7Cu-1.7Bi+α | 20-38 | 180 |
| | PS20BR-600A-HLS7 | Low 0.1% silver | Sn-0.1Ag-0.7Cu-2.0Bi+β | 20-38 | 180 |
| | PS58BR-450A-KL1 | Low melting point(SnBi) | Sn-58Bi | 25-45 | 180 |

Naming of solder paste product

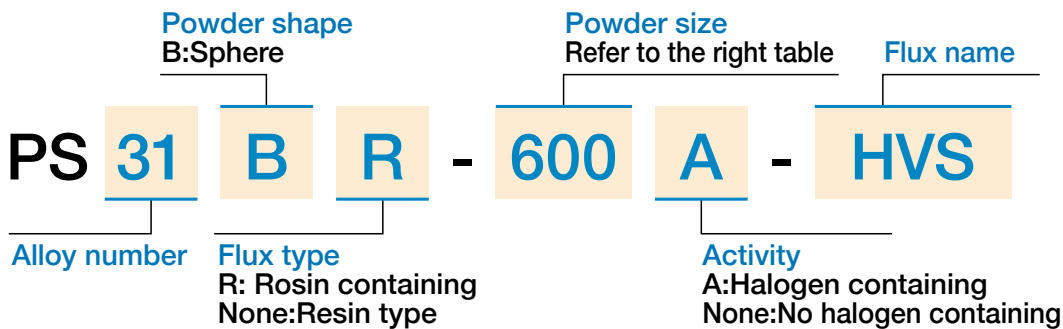


Table of solder powder size

| Number | Size (μm) |
|--------|-----------|
| 450 | 25~45 |
| 600 | 20~38 |
| 650 | 20~32 |
| 700 | 15~25 |
| 800 | 5~15 |

Solder alloy list

| Classification | Alloy number | Alloy composition | Sn | Ag | Cu | In | Bi | Sb | Pb | Other element | Melting point (°C) |
|------------------|--------------|----------------------------------|---------|-----|-----|-----|------|-----|------|---------------|--------------------|
| Sn-Ag-Cu | 31 | Sn-3.0Ag-0.5Cu | Balance | 3.0 | 0.5 | - | - | - | - | - | 219 |
| Durability type | 48 | Sn-3.2Ag-0.5Cu-4.0Bi-3.5Sb-Ni-Co | Balance | 3.2 | 0.5 | - | 4.0 | 3.5 | - | ● | 223 |
| Low 1.1% silver | 24 | Sn-1.1Ag-0.7Cu-1.7Bi+α | Balance | 1.1 | 0.7 | - | 1.7 | - | - | ● | 223 |
| Low 0.1% silver | 20 | Sn-0.1Ag-0.7Cu-2.0Bi+β | Balance | 0.1 | 0.7 | - | 2.0 | - | - | ● | 225 |
| Low melting (In) | 37 | Sn-3.5Ag-8.0In-0.5Bi | Balance | 3.5 | - | 8.0 | 0.5 | - | - | - | 207 |
| Low melting (Bi) | 58 | Sn-58Bi | Balance | - | - | - | 58.0 | - | - | - | 138 |
| Sn-Pb | 10 | Sn-37Pb | Balance | - | - | - | - | - | 37.0 | - | 183 |
| | 60 | Sn-36Pb-2Ag | Balance | 2.0 | - | - | - | - | 36.0 | - | 190 |